

Chapter E: BGA

4. References

4.1 Recommended reading

[1] C. A. Harper and R. N. Sampson (eds.), "Electronic materials and processes handbook", ISBN 0-07-054299-6, McGraw-Hill, New York 1994

[2] J. S. Hwang, "Ball Grid Array & Fine Pitch Peripheral Interconnections", ISBN 0 901150 29 0, Electrochemical Publications Ltd, Isle of Man 1995

[3] T. L. Landers et al, "Electronics Manufacturing Processes", ISBN 0-13-176470-5, Prentice Hall, Englewood Cliffs 1994

[4] J. H. Lau (ed.), "Ball grid array technology," ISBN 0-07-036608-X, McGraw-Hill, New York 1995

[5] Joint Industry Standard ANSI/J-STD-013, "Implementation of Ball Grid Array and Other High Density Technology", IPC - The institute for Interconnecting and Packaging Electronics Circuits, 2215 Sanders Road, Northbrook, IL 60062-6135, USA

4.2 National reports

VI Forskningsrapport V040037A "Utvärdering av byggsättsteknik för produktion med BGA- och fine-pitch QFP-kapslar," R. Rörgren, P. Carlsson, J. Liu, 1995 (in Swedish)

Rapport BEE/A/BE/001 "Produktionskrav BGA på mönsterkort", Lars Wåhlström, Berifors (in Swedish)

Rapport BEE/C/BE/002 "Process för montering av BGA till mönsterkort/Konstruktionsmetodik för kretskort med BGA", Lars Wåhlström, Berifors (in Swedish)

4.3 Papers

Paper "BGA-MCM technology for harsh environmental applications", P. Haglund, P. Frisk, J.-O. Andersson, ISHM-Europe, 14-16 May 1997, Venice, Italy

Paper "BGAs for high reliability applications," R. Ghaffarian, Electronics Packaging & Production, Vol. 38, No. 3, pp.45-52, March 1998.

Seminar presentation "Reliability of BGA Packages," Andrew Mawer, IVF Seminar on BGA Reliability in Harsh Environments, November 20, 1997,

4.4 Conferences

APEX: <http://www.ipc.org/html/apex.htm>

IMAPS: <http://www.imaps.org>

Surface Mount International: <http://www.smta-international.com>